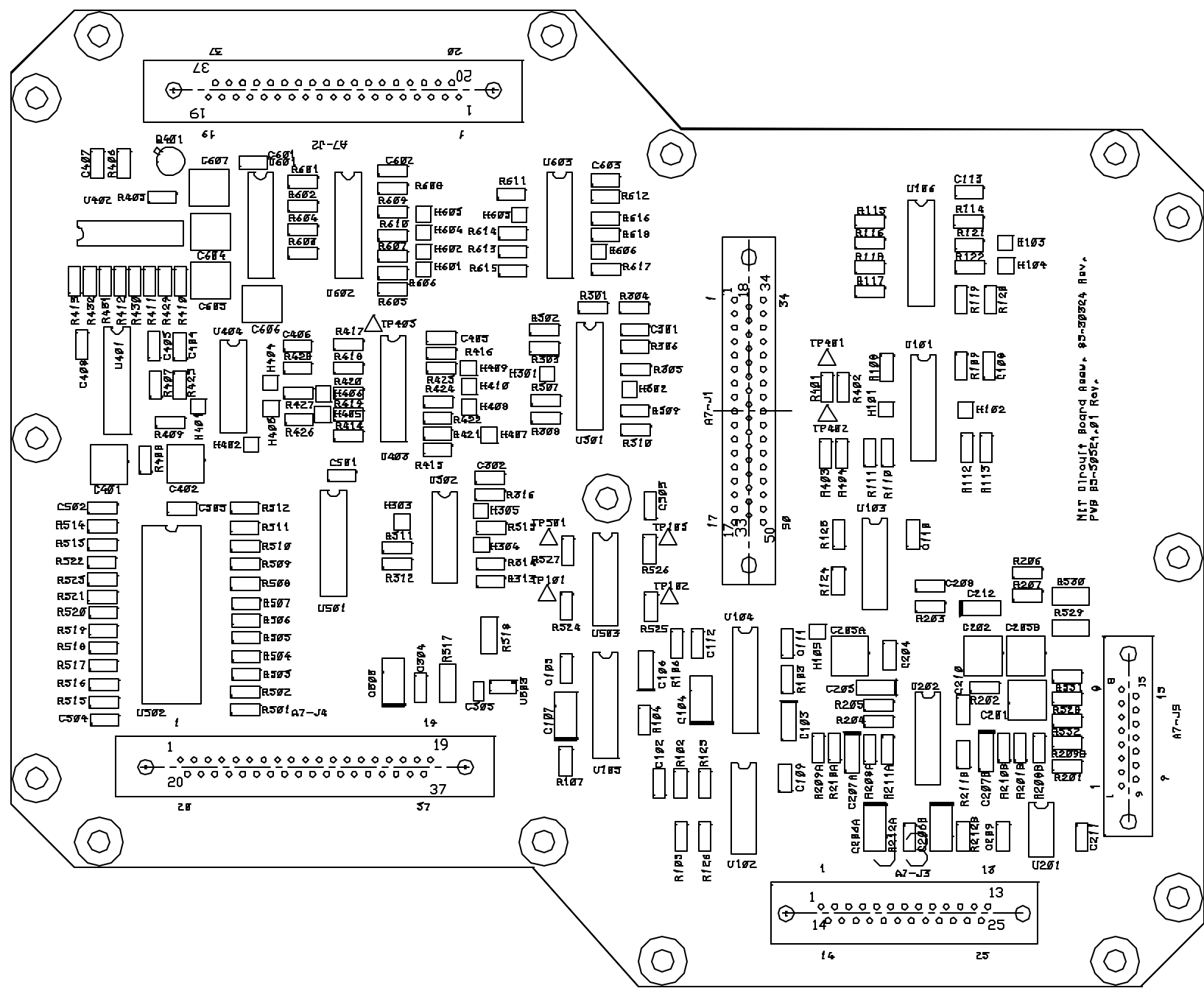


8 7 6 5 4 3 2 1

REVISIONS					
ECD	REV	DESCRIPTION	CHECKED	APPROVED	DATE
85-144	01	INITIAL RELEASE			

D  
C  
B  
A

.06 MAX LEAD HEIGHT  
.75 MAX COMPONENT HEIGHT



MIT Electronics Board Name: 85-30324 Rev.  
PWB 85-30324, 01 Rev.

- NOTES:
- REFER TO MIT DRAWING 85- FOR SCHEMATIC CONNECTION AND WIRE ASSIGNMENTS.
  - FABRICATE IAW NASA SPEC NHB5300.4(3G)
  - SOLDER IAW NASA SPECIFICATION NAS-STD-8739.2 AND NAS-STD-8739.3.
  - PERFORM CONTACT RETENTION TEST ON ALL CONTACTS PER MSFC-STD-781. RECORD RESULTS IN A.W.D.
  - ELECTRICAL TESTS ARE TO BE PERFORMED IAW NHB5300.4(3G). RECORD RESULTS IN A.W.D.
  - TORQUE HARDWARE TO 32 IN-OZ. SPOTBOND WITH F/N 19.
  - ITEM IS STATIC SENSITIVE. HANDLE IAW MIT PROCEDURE 99-01003.
  - MASK FOR CONFORMAL COAT AS INDICATED. MASK ALL WIRES FROM CONNECTORS.
  - VACUUM BAKE ALL CONNECTORS AT 80C FOR 72 HOURS PRIOR TO KITTING AND INSTALLATION.
  - CONFORMAL COAT USING F/N 16.  
-CURE AT 25C, AMBIENT PRESSURE FOR 8 HOURS.  
-REMOVE MASKING AND MASKING RESIDUE PRIOR TO BAKE.  
-VACCUM BAKE AT 65C, 10<sup>-4</sup> TORR FOR 24 HOURS.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCE: ANGLES +/- .1° 3 PLACE DECIMALS +/- .005 2 PLACE DECIMALS +/- .01		NAME	DATE	Massachusetts Institute of Technology Center for Space Research VOILA	
DRAWN M. SMITH		6/18/04		PWA, MIT ELECTRONICS	
MATERIAL N/A		CHECKED		SIZE J	
FINISH N/A		APPROVED		FSCM NO. 80230	
85-30324		RELEASED		DWC NO. 30-30324	
NEXT ASSEMBLY USED ON		CAD FILE 85-		SCALE 1:1	
APPLICATION				SHEET 1 OF 1	

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